



- NOTES:
1. SHADED AREA METALLIZATION.
 2. FINISH: Au PLATE 100uIN. MIN. THICKNESS OVER Ni LEAD. Au PLATING THICKNESS IS MEASURED ON LEAD.
 3. NO BLISTERS ON Au PLATING AFTER 3 MINUTES AT 450°C AS SEEN UNDER 10X MAGNIFICATION.
 4. HERMETICITY 1.0X10⁻⁹Pa·m³/s AT 1.0 ATM DIFFERENTIAL.
 5. LEAD PULL STRENGTH 2 POUND MINIMUM PULLED 90° TO PLANE OF CERAMIC.
 6. LEAD FATIGUE MUST PASS (2) 90° ARCS WITH 8 OZ WEIGHT.
 7. ISOLATION RESISTANCE ≤ 5X10⁻⁹A AT 100V D.C.
 8. PLATING RACK POINT MARKS TO BE PERMITTED ON THIS AREA. (NOT APPLY NOTE 2,3)
 9. GENERAL SPECIFICATION: MS-1001 (LATEST VERSION)
VISUAL INSPECTION SPECIFICATION: MAS-1002 (LATEST VERSION)

MODIFICATIONS						NAME	PB-100 PKG		TOLERANCES:	3RD ANGLE	CONFIRMED	CONFIRMED
								UNLESS OTHERWISE SPECIFIED		PROJECTION	OCT.1.'01	OCT.1.'01
						MATERIAL	SCALE	.XX ±		APPROVED	S.ADACHI	T.NAGASHIMA
						AS INDICATED	10/1	.XXX ±.005 (0.13)		OCT.2.'01	CONFIRMED	DRAWN
										S.MORIOKA	K.SAHARA	S.NAITO
CHANGE		DATE	APPROVED	CONFIRMED	DRAWN	KYOCERA CORPORATION KYOTO JAPAN			DWG No.	PGMR-A1350		